

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE


Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: METHOD OF MAKING A SEMICONDUCTOR PACKAGE
DEVICE THAT INCLUDES A CONDUCTIVE TRACE WITH
RECESSED AND NON-RECESSED PORTIONS
Serial No.: 10/059,686 Filed: January 29, 2002
Examiner: Zarneke, D. Group Art Unit: 2827
Atty. Docket No.: BDG005-1

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313

TRANSMITTAL OF FORMAL DRAWINGS

Attached please find the formal drawings (29 sheets) for this application.

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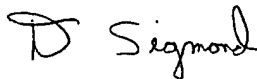


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12, 15, 03

Date of Signature

Respectfully submitted,



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